

| L Number | Hits | Search Text | DB | Time stamp |
|----------|------|--|----------------------------------|------------------|
| 1 | 3759 | 438/595.ccls. 438/638.ccls. 438/639.ccls. 438/640.ccls. | USPAT; | 2004/10/18 09:51 |
| 2 | 3 | 438/672.ccls. 438/675.ccls. 257/775.ccls. 6740916.pn. 6617631.pn. 6083788.pn. | US-PGPUB USPAT; | 2004/10/18 09:54 |
| 3 | 58 | (438/595.ccls. 438/638.ccls. 438/639.ccls. 438/640.ccls. 438/672.ccls. 438/675.ccls. 257/775.ccls.) and ((gate wordline bitline ((word bit metal conduct\$6) adj (line trace runner interconnect\$6))) same (hole opening via trench groove window) same (contact plug stud land\$6 pad) same (taper\$6 funnel conical cone)) | US-PGPUB USPAT; | 2004/10/18 10:25 |
| 4 | 559 | ((gate wordline bitline ((word bit metal conduct\$6) adj (line trace runner interconnect\$6))) same (hole opening via trench groove window) same (contact plug stud land\$6 pad) same (taper\$6 funnel conical cone)) and (semiconductor wafer silicon substrate) | USPAT; | 2004/10/18 10:29 |
| 9 | 361 | ((hole opening via trench groove window) with (liner spacer sidewall (side adj wall))) and (contact plug stud land\$6 pad) and (taper\$6 funnel conical cone (isotropic\$8 with etch\$6)) and (semiconductor wafer silicon substrate) | EPO; JPO; DERWENT; IBM_TDB | 2004/10/18 10:22 |
| 12 | 784 | ((hole opening via trench groove window) with (liner spacer sidewall (side adj wall))) same (contact plug stud land\$6 pad) same (taper\$6 funnel conical cone)) and (semiconductor wafer silicon substrate) | USPAT; | 2004/10/18 10:28 |
| 10 | 118 | (438/595.ccls. 438/638.ccls. 438/639.ccls. 438/640.ccls. 438/672.ccls. 438/675.ccls. 257/775.ccls.) and ((gate wordline bitline ((word bit metal conduct\$6) adj (line trace runner interconnect\$6))) same (hole opening via trench groove window) same (contact plug stud land\$6 pad) same (taper\$6 funnel conical cone (isotropic\$8 with etch\$6))) | US-PGPUB USPAT; | 2004/10/18 10:30 |
| 11 | 87 | (438/595.ccls. 438/638.ccls. 438/639.ccls. 438/640.ccls. 438/672.ccls. 438/675.ccls. 257/775.ccls.) and (((hole opening via trench groove window) with (liner spacer sidewall (side adj wall))) same (contact plug stud land\$6 pad) same (taper\$6 funnel conical cone)) | USPAT; | 2004/10/18 11:06 |
| 13 | 111 | ((gate wordline bitline ((word bit metal conduct\$6) adj (line trace runner interconnect\$6))) same ((hole opening via trench groove window) with (liner spacer sidewall (side adj wall))) same (contact plug stud land\$6 pad) same (taper\$6 funnel conical cone)) and (semiconductor wafer silicon substrate) | USPAT; | 2004/10/18 11:40 |
| 7 | 204 | (gate wordline bitline ((word bit metal conduct\$6) adj (line trace runner interconnect\$6))) and (hole opening via trench groove window) and (contact plug stud land\$6 pad) and (taper\$6 funnel conical cone) and (semiconductor wafer silicon substrate) | EPO; JPO; DERWENT; IBM_TDB | 2004/10/18 12:07 |
| 8 | 209 | ((hole opening via trench groove window) with (liner spacer sidewall (side adj wall))) and (contact plug stud land\$6 pad) and (taper\$6 funnel conical cone) and (semiconductor wafer silicon substrate) | EPO; JPO; DERWENT; IBM_TDB | 2004/10/18 12:50 |
| 5 | 317 | ((gate wordline bitline ((word bit metal conduct\$6) adj (line trace runner interconnect\$6))) same ((hole opening via trench groove window) with (taper\$6 funnel conical cone)) same (contact plug stud land\$6 pad)) and (semiconductor wafer silicon substrate) | USPAT; | 2004/10/18 14:12 |